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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

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Product Status	Not For New Designs
Core Processor	H8S/2000
Core Size	16-Bit
Speed	20MHz
Connectivity	IrDA, SCI
Peripherals	POR, PWM, WDT
Number of I/O	74
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BFQFP
Supplier Device Package	100-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/df2144afa20v

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Item	Page	Revision (See Manual for Details)				
26.3.4 A/D Conversion	831	Note *4 added to table condition				
Characteristics Table 26.27 A/D		Condition C: $V_{cc} = 3.0 \text{ V}$ to 3.6 V^{*4} , $AV_{cc} = 3.0 \text{ V}$ to 3.6 V^{*4} , $AV_{ref} = 3.0 \text{ V}$ to AV_{cc}^{*4} , $V_{cc}B = 3.0 \text{ V}$ to 5.5 V^{*4} ,				
Conversion		Note 4 amended				
Characteristics (CIN15 to CIN0 Input: 134/266- State Conversion)		Note: 4. When using CIN, the applicable range is $V_{\rm cc}$ = 3.0 V to 3.6 V,				
26.3.6 Flash Memory	833	Table 26.29 amended				
Characteristics Table 26.29 Flash		Item amended (Before) Wait time after dummy write \rightarrow (After) Wait time after H'FF dummy write				
Memory Characteristics		Symbol of wait time after SWE-bit clear (Before) $\Theta \rightarrow$ (After) θ				
(Programming/erasing operating range)		Item Symbol Min Typ Max Unit Condition Reprogramming count N _{wec} 100** 10000** — Times Data retention time*** t _{cee} 10 — — Years Programming Wait time after SWE-bit setting** x 1 — — µs				
	834	Notes 8 to 10 added				
	004	Notes: 8. Minimum number of times for which all characteristics are guaranteed after rewriting (Guarantee range is 1 to minimum value).				
		 Reference value for 25°C (as a guideline, rewriting should normally function up to this value). 				
		 Data retention characteristic when rewriting is performed within the specification range, including the minimum value. 				
26.4.3 AC	849	Unit of t _{IMMH} amended				
Characteristics		(Before) \longrightarrow (After) ns				
Table 26.35 Control Signal Timing						
Table 26.37 Timing of	854,	Units of $t_{_{PRS}},t_{_{PRH}},t_{_{FTIS}},t_{_{FTCS}},t_{_{TMRS}},t_{_{TMCS}}$ amended				
On-Chip Supporting Modules (1)	855	(Before) \longrightarrow (After) ns				
		Units of $t_{_{\text{FTCWL}}}$, $t_{_{\text{TMCWL}}}$, synchronous $t_{_{\text{Scyc}}}$ amended				
		$(\text{Before}) \longrightarrow (\text{After}) t_{_{\text{cyc}}}$				
		Unit of t _{sckf} amended				
		(Before) 1.5 \rightarrow (After) t _{cyc}				
26.4.4 A/D Conversion	860	Table condition amended				
Characteristics		Table condition A (Before), Ta = -20 to $+75^{\circ}$ C (regular				
Table 26.41 A/D Conversion Characteristics (CIN15 to CIN0 Input: 134/266- State Conversion)		specifications), Ta = -40 to $+85^{\circ}$ C (wide-range specifications) \rightarrow (After) Ta = -20 to $+75^{\circ}$ C				

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	Pin Name							
Pin No.	Expan	ded Modes	Single-Chip Modes					
FP-100B TFP-100B	Mode 1	Mode 2 (EXPE = 1) Mode 3 (EXPE = 1)	Mode 2 (EXPE = 0) Mode 3 (EXPE = 0)	Flash Memory Writer Mode				
1	RES	RES	RES	RES				
2	XTAL	XTAL	XTAL	XTAL				
3	EXTAL	EXTAL	EXTAL	EXTAL				
4	VCCB	VCCB	VCCB	VCC				
5	MD1	MD1	MD1	VSS				
6	MD0	MD0	MD0	VSS				
7	NMI	NMI	NMI	FA9				
8	STBY	STBY	STBY	VCC				
9	VCC2	VCC2	VCC2	VCC				
10	PA7/CIN15/ KIN15/PS2CD	A23/PA7/CIN15/ KIN15/PS2CD	PA7/CIN15/ KIN15/PS2CD	NC				
11	PA6/CIN14/ KIN14/PS2CC	A22/PA6/CIN14/ KIN14/PS2CC	PA6/CIN14/ KIN14/PS2CC	NC				
12	P52/SCK0/SCL0	P52/SCK0/SCL0	P52/SCK0/SCL0	NC				
13	P51/RxD0	P51/RxD0	P51/RxD0	FA17				
14	P50/TxD0	P50/TxD0	P50/TxD0	NC				
15	VSS	VSS	VSS	VSS				
16	P97/WAIT/SDA0	P97/WAIT/SDA0	P97/SDA0	VCC				
17	φ/P96/EXCL	φ/P96/EXCL	P96/ø/EXCL	NC				
18	AS/IOS	AS/IOS	P95/CS1	FA16				
19	HWR	HWR	P94/IOW	FA15				
20	PA5/CIN13/ KIN13/PS2BD	A21/PA5/CIN13/ KIN13/PS2BD	PA5/CIN13/ KIN13/PS2BD	NC				
21	PA4/CIN12/ KIN12/PS2BC	A20/PA4/CIN12/ KIN12/PS2BC	PA4/CIN12/ KIN12/PS2BC	NC				
22	RD	RD	P93/IOR	WE				
23	P92/IRQ0	P92/IRQ0	P92/IRQ0	VSS				
24	P91/IRQ1	P91/IRQ1	P91/IRQ1	VCC				

Table 1.2 (b) H8S/2147N Pin Functions in Each Operating Mode

		Pin No.	_	
Туре	Symbol	FP-100B TFP-100B	I/O	Name and Function
Bus control	WAIT	16	Input	Wait: Requests insertion of a wait state in the bus cycle when accessing external 3-state address space.
	RD	22	Output	Read: When this pin is low, it indicates that the external address space is being read.
	HWR	19	Output	High write: When this pin is low, it indicates that the external address space is being written to. The upper half of the data bus is valid.
	LWR	25	Output	Low write: When this pin is low, it indicates that the external address space is being written to. The lower half of the data bus is valid.
	AS/IOS	18	Output	Address strobe: When this pin is low, it indicates that address output on the address bus is valid.
Interrupt signals	NMI	7	Input	Nonmaskable interrupt: Requests a nonmaskable interrupt.
	IRQ0 to IRQ7	23 to 25, 97 to 99, 34, 35	Input	Interrupt request 0 to 7: These pins request a maskable interrupt.
16-bit free- running	FTCI	26	Input	FRT counter clock input: Input pin for an external clock signal for the free-running counter (FRC).
timer (FRT)	FTOA	27	Output	FRT output compare A output: The output compare A output pin.
	FTOB	34	Output	FRT output compare B output: The output compare B output pin.
	FTIA	28	Input	FRT input capture A input: The input capture A input pin.
	FTIB	29	Input	FRT input capture B input: The input capture B input pin.
	FTIC	32	Input	FRT input capture C input: The input capture C input pin.
	FTID	33	Input	FRT input capture D input: The input capture D input pin.

6.1.3 Pin Configuration

Table 6.1 summarizes the pins of the bus controller.

Table 6.1	Bus Controller Pins
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Name	Symbol	I/O	Function
Address strobe	ĀS	Output	Strobe signal indicating that address output on address bus is enabled (when IOSE bit is 0)
I/O select	ĪOS	Output	I/O select signal (when IOSE bit is 1)
Read	RD	Output	Strobe signal indicating that external space is being read
High write	HWR	Output	Strobe signal indicating that external space is being written to, and that the upper data bus (D15 to D8) is enabled
Low write	LWR	Output	Strobe signal indicating that external space is being written to, and that the lower data bus (D7 to D0) is enabled
Wait	WAIT	Input	Wait request signal when external 3-state access space is accessed

6.1.4 Register Configuration

Table 6.2 summarizes the registers of the bus controller.

Table 6.2Bus Controller Registers

Name	Abbreviation	R/W	Initial Value	Address*			
Bus control register	BCR	R/W	H'D7	H'FFC6			
Wait state control register	WSCR	R/W	H'33	H'FFC7			
Noto: * Lower 16 bits of the address							

Note: * Lower 16 bits of the address.

Bit 3	Bit 2	
MD1	MD0	Description
0	0	Normal mode
	1	Repeat mode
1	0	Block transfer mode
	1	_

Bits 3 and 2—DTC Mode (MD1, MD0): These bits specify the DTC transfer mode.

Bit 1—DTC Transfer Mode Select (DTS): Specifies whether the source side or the destination side is set to be a repeat area or block area, in repeat mode or block transfer mode.

Bit 1

DTS	Description
0	Destination side is repeat area or block area
1	Source side is repeat area or block area

Bit 0-DTC Data Transfer Size (Sz): Specifies the size of data to be transferred.

Bit 0

Sz	Description
0	Byte-size transfer
1	Word-size transfer

7.3.9 Operation Timing

Figures 7.10 to 7.12 show examples of DTC operation timing.

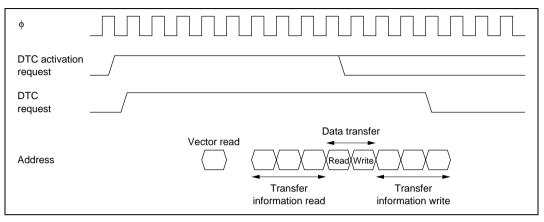


Figure 7.10 DTC Operation Timing (Normal Mode or Repeat Mode)

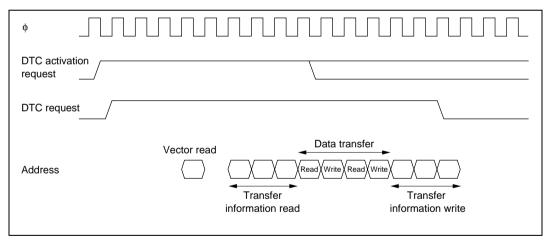


Figure 7.11 DTC Operation Timing (Block Transfer Mode, with Block Size of 2)

	Selection Me	thod and I	Pin Functi	ons					
PB4/D4	The pin function is switched as shown below according to the combination of the operating mode, bit PB4DDR, and bit ABW in WSCR.								
	Operating mode		Modes 1 (EXPE			Modes (EXPE			
	ABW	0		1		_			
	PB4DDR		0		1	0	1		
	Pin function	D4 I/O pin	PB4 input p		34 ut pin in	PB4 put pin	PB4 output pin		
PB3/D3/CS4	The pin functi the operating bit PB3DDR.								
	Operating mode		lodes 1, 2, (EXPE = 1)		Modes 2, 3 (EXPE = 0)				
	HI12E				Either cleared to 0		1		
	CS4E		_				1		
	ABW	0 1		-	_	_			
	PB3DDR	_	0	1	0	1	—		
	Pin function	D3	PB3	PB3	PB3	PB3	CS4		
		I/O pin	input pin	output pin	input pin	output pin	input pin		
PB2/D2/CS3	The pin functi the operating bit PB2DDR.	mode, bits	HI12E and	I CS3E in S					
	Operating mode		lodes 1, 2, (EXPE = 1)		Modes 2, 3 (EXPE = 0)				
	HI12E		_		Either cleared to 0		1		
	CS3E		—				1		
	CS3E ABW	0		1	-	_	1		
		0	0	1		1	1 — —		

10.4 Operation

A PWM waveform like the one shown in figure 10.3 is output from the PWMX pin. When OS = 0, the value in DADR corresponds to the total width (T_L) of the low (0) pulses output in one conversion cycle (256 pulses when CFS = 0, 64 pulses when CFS = 1). When OS = 1, the output waveform is inverted and the DADR value corresponds to the total width (T_H) of the high (1) output pulses. Figure 10.4 shows the types of waveform output available.

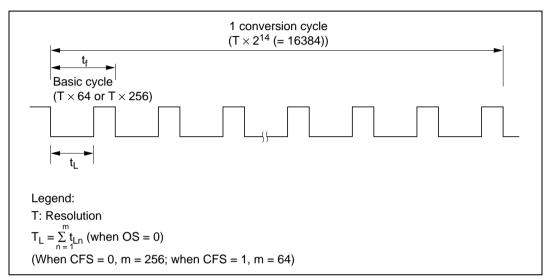
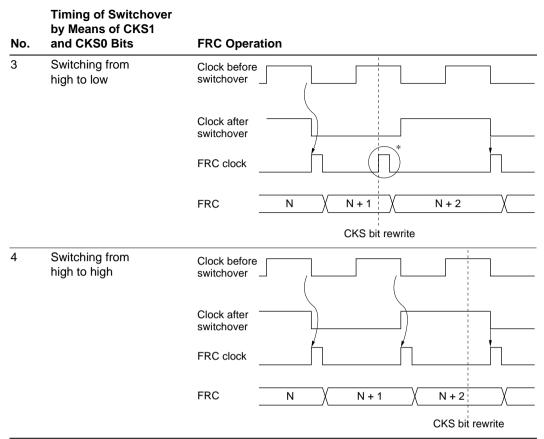


Figure 10.3 PWM D/A Operation

Table 10.4 summarizes the relationships of the CKS, CFS, and OS bit settings to the resolution, base cycle, and conversion cycle. The PWM output remains flat unless DADR contains at least a certain minimum value. Table 10.4 indicates the range of DADR settings that give an output waveform like the one in figure 10.3, and lists the conversion cycle length when low-order DADR bits are kept cleared to 0, reducing the conversion precision to 12 bits or 10 bits.





Note: * Generated on the assumption that the switchover is a falling edge; FRC is incremented.



12.2.4 Timer Control Register (TCR)

Bit	7	6	5	4	3	2	1	0
	CMIEB	CMIEA	OVIE	CCLR1	CCLR0	CKS2	CKS1	CKS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

TCR is an 8-bit readable/writable register that selects the clock source and the time at which TCNT is cleared, and enables interrupts.

TCR is initialized to H'00 by a reset and in hardware standby mode.

For details of the timing, see section 12.3, Operation.

Bit 7—Compare-Match Interrupt Enable B (CMIEB): Selects whether the CMFB interrupt request (CMIB) is enabled or disabled when the CMFB flag in TCSR is set to 1.

Note that a CMIB interrupt is not requested by TMRX, regardless of the CMIEB value.

Bit 7

CMIEB	Description	
0	CMFB interrupt request (CMIB) is disabled	(Initial value)
1	CMFB interrupt request (CMIB) is enabled	

Bit 6—Compare-Match Interrupt Enable A (CMIEA): Selects whether the CMFA interrupt request (CMIA) is enabled or disabled when the CMFA flag in TCSR is set to 1.

Note that a CMIA interrupt is not requested by TMRX, regardless of the CMIEA value.

Bit 6

CMIEA	Description	
0	CMFA interrupt request (CMIA) is disabled	(Initial value)
1	CMFA interrupt request (CMIA) is enabled	

Renesas

	Operating Frequency φ (MHz)													
Bit Rate (bits/s)		φ = 14 M	ИНz	¢) = 14.745	6 MHz		φ = 16 M	/IHz	φ = 17.2032 MHz				
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)		
110	2	248	-0.17	3	64	0.70	3	70	0.03	3	75	0.48		
150	2	181	0.16	2	191	0.00	2	207	0.16	2	223	0.00		
300	2	90	0.16	2	95	0.00	2	103	0.16	2	111	0.00		
600	1	181	0.16	1	191	0.00	1	207	0.16	1	223	0.00		
1200	1	90	0.16	1	95	0.00	1	103	0.16	1	111	0.00		
2400	0	181	0.16	0	191	0.00	0	207	0.16	0	223	0.00		
4800	0	90	0.16	0	95	0.00	0	103	0.16	0	111	0.00		
9600	0	45	-0.93	0	47	0.00	0	51	0.16	0	55	0.00		
19200	0	22	-0.93	0	23	0.00	0	25	0.16	0	27	0.00		
31250	0	13	0.00	0	14	-1.70	0	15	0.00	0	16	1.20		
38400	_	_	_	0	11	0.00	0	12	0.16	0	13	0.00		

Operating Frequency φ (MHz)

		φ = 18 M	ЛНz	ф	= 19.660	8 MHz		φ = 20 MHz		
Bit Rate (bits/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	
110	3	79	-0.12	3	86	0.31	3	88	-0.25	
150	2	233	0.16	2	255	0.00	3	64	0.16	
300	2	116	0.16	2	127	0.00	2	129	0.16	
600	1	233	0.16	1	255	0.00	2	64	0.16	
1200	1	116	0.16	1	127	0.00	1	129	0.16	
2400	0	233	0.16	0	255	0.00	1	64	0.16	
4800	0	116	0.16	0	127	0.00	0	129	0.16	
9600	0	58	-0.69	0	63	0.00	0	64	0.16	
19200	0	28	1.02	0	31	0.00	0	32	-1.36	
31250	0	17	0.00	0	19	-1.70	0	19	0.00	
38400	0	14	-2.34	0	15	0.00	0	15	1.73	

Bit 1—Host Interface Enable (HIE): Enables or disables CPU access to the host interface registers. When enabled, the host interface registers (HICR, IDR1, ODR1, STR1, IDR2, ODR2, and STR2) can be accessed.

Bit 1

HIE	Description
0	Host interface register (HICR, IDR1, ODR1, STR1, IDR2, ODR2, STR2), CPU access is disabled (Initial value)
1	Host interface register (HICR, IDR1, ODR1, STR1, IDR2, ODR2, STR2), CPU access is enabled

18.2.2 System Control Register 2 (SYSCR2)

Bit	7	6	5	4	3	2	1	0
	KWUL1	KWUL0	P6PUE	_	SDE	CS4E	CS3E	HI12E
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	—	R/W	R/W	R/W	R/W

SYSCR2 is an 8-bit readable/writable register which controls chip operations. Host interface functions are enabled or disabled by the HI12E bit in SYSCR2. The number of channels that can be used can be extended to a maximum of four by means of the CS3E bit and CS4E bit. SYSCR2 is initialized to H'00 by a reset and in hardware standby mode.

Bits 7 and 6—Key Wakeup Level 1 and 0 (KWUL1, KWUL0): The port 6 input level can be set and changed by software. For details see section 8, I/O Ports.

Bit 5—Port 6 Input Pull-Up Extra (P6PUE): Controls and selects the current specification for the port 6 MOS input pull-up function connected by means of KMPCR settings. For details see section 8, I/O Ports.

Bit 4—Reserved: Do not write 1 to this bit.



22.6.1 Boot Mode

When boot mode is used, the flash memory programming control program must be prepared in the host beforehand. The channel 1 SCI to be used is set to asynchronous mode.

When a reset-start is executed after this group MCU's pins have been set to boot mode, the boot program built into the MCU is started and the programming control program prepared in the host is serially transmitted to the MCU via the SCI. In the MCU, the programming control program received via the SCI is written into the programming control program area in on-chip RAM. After the transfer is completed, control branches to the start address of the programming control program area and the programming control program execution state is entered (flash memory programming is performed).

The transferred programming control program must therefore include coding that follows the programming algorithm given later.

The system configuration in boot mode is shown in figure 22.7, and the boot program mode execution procedure in figure 22.8.

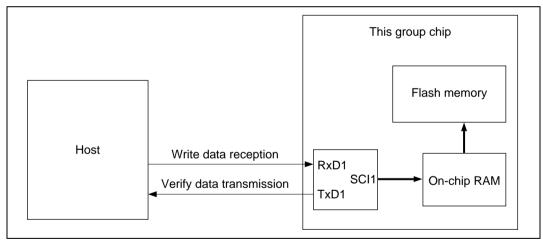


Figure 22.7 System Configuration in Boot Mode



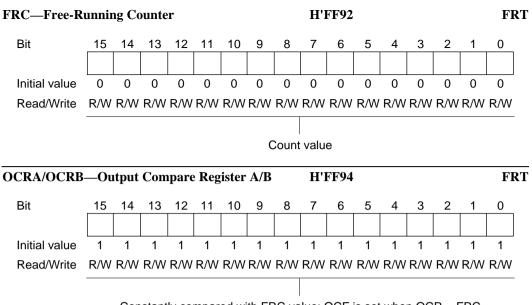
Table 26.25 I²C Bus Timing

Conditions: $V_{cc} = 4.0 \text{ V}$ to 5.5 V, $V_{cc} = 2.7 \text{ V}$ to 3.6 V (3 V version), $V_{ss} = 0 \text{ V}$, $\phi = 5 \text{ MHz}$ to maximum operating frequency

		Ra	atings				
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	Notes
SCL input cycle time	t _{SCL}	12	_	_	t _{cyc}		Figure 26.28
SCL input high pulse width	t _{sclh}	3	—	—	t _{cyc}		_
SCL input low pulse width	t _{SCLL}	5	—	—	t _{cyc}		_
SCL, SDA input rise time	t _{sr}	_	—	7.5*	t _{cyc}		_
SCL, SDA input fall time	t _{sr}	—	—	300	ns		_
SCL, SDA output fall time	t _{of}	20 + 0.1 Cb	_	250	ns		-
SCL, SDA input spike pulse elimination time	t _{sp}	_	—	1	t _{cyc}		-
SDA input bus free time	t _{BUF}	5	_	—	t _{cyc}		-
Start condition input hold time	t _{stah}	3	—	—	t _{cyc}		_
Retransmission start condition input setup time	t _{stas}	3	_	_	t _{cyc}		_
Stop condition input setup time	t _{stos}	3	—	—	t _{cyc}		_
Data input setup time	\mathbf{t}_{sdas}	0.5	—	—	t _{cyc}		_
Data input hold time	t _{sdah}	0	—		ns		_
SCL, SDA capacitive load	C,	_		400	pF		

Note: * 17.5t_{cyc} can be set according to the clock selected for use by the l²C module. For details, see section 16.4, Usage Notes.

Lower Address	Register Name	H8S/2148 Group Selection Cor		H8S/2147N Regis Conditio		H8S/2144 Group Register Selection Conditions	Module Name
H'FEF3	DTVECR	No conditions		—		_	DTC
H'FEF4	ABRKCR	No conditions		No conditions		No conditions	Interrupt
H'FEF5	BARA	-					controller
H'FEF6	BARB	-					
H'FEF7	BARC	-					
H'FF80	FLMCR1	FLSHE = 1 in STCR		FLSHE = 1 in STCR		FLSHE = 1 in STCR	Flash
H'FF81	FLMCR2	-					memory
H'FF82	PCSR	FLSHE = 0 in STCR		FLSHE = 0 in STCR		—	PWM
	EBR1	FLSHE = 1 in STCR		FLSHE = 1 in STCR		FLSHE = 1 in STCR	Flash memory
H'FF83	SYSCR2	FLSHE = 0 in STCR		FLSHE = 0 in STCR		—	HIF
	EBR2	FLSHE = 1 in STCR		FLSHE = 1 in STCR		FLSHE = 1 in STCR	Flash memory
H'FF84	SBYCR	FLSHE = 0 in STCR		FLSHE = 0 in STCR		FLSHE = 0 in STCR	System
H'FF85	LPWRCR	-					
H'FF86	MSTPCRH	-					
H'FF87	MSTPCRL	-					
H'FF88	SMR1	MSTP6 = 0, IICE = 0 in STCR		MSTP6 = 0, IICE = 0	in STCR	MSTP6 = 0, IICE = 0 in STCR	SCI1
	ICCR1	MSTP3 = 0, IICE = 1	in STCR	MSTP3 = 0, IICE = 1	in STCR	—	IIC1
H'FF89	BRR1	MSTP6 = 0, IICE = 0	in STCR	MSTP6 = 0, IICE = 0	in STCR	MSTP6 = 0, IICE = 0 in STCR	SCI1
	ICSR1	MSTP3 = 0, IICE = 1	in STCR	MSTP3 = 0, IICE = 1	in STCR	—	IIC1
H'FF8A	SCR1	MSTP6 = 0		MSTP6 = 0		MSTP6 = 0	SCI1
H'FF8B	TDR1	-					
H'FF8C	SSR1						
H'FF8D	RDR1						
H'FF8E	SCMR1	MSTP6 = 0, IICE = 0	in STCR	MSTP6 = 0, IICE = 0	in STCR	MSTP6 = 0, IICE = 0 in STCR	
	ICDR1	MSTP3 = 0, IICE = 1 in STCR	ICE = 1 in ICCR1	MSTP3 = 0, IICE = 1 in STCR	ICE = 1 in ICCR1	-	IIC1
	SARX1		ICE = 0 in ICCR1		ICE = 0 in ICCR1		
H'FF8F	ICMR1	1	ICE = 1 in ICCR1		ICE = 1 in ICCR1		
	SAR1		ICE = 0 in ICCR1		ICE = 0 in ICCR1		
H'FF90	TIER	MSTP13 = 0	1	MSTP13 = 0		MSTP13 = 0	FRT
H'FF91	TCSR	4					
H'FF92	FRCH	4					



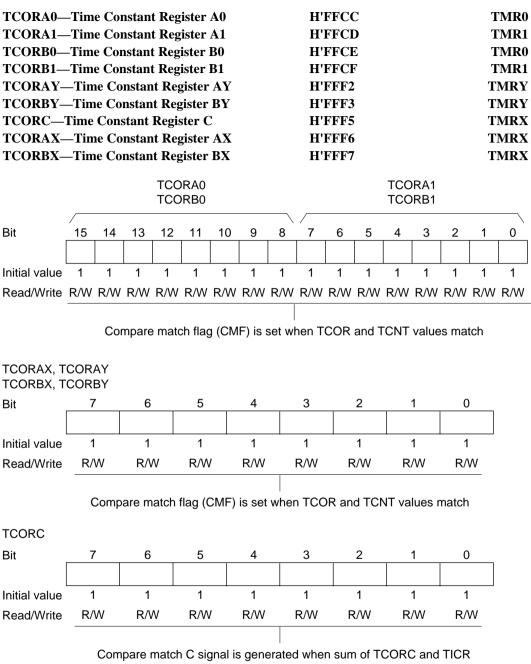
Constantly compared with FRC value; OCF is set when OCR = FRC



P8DR—Port 8	Data Reg	ister			Port 8			
Bit	7	6	5	4	3	2	1	0
	_	P86DR	P85DR	P84DR	P83DR	P82DR	P81DR	P80DR
Initial value	1	0	0	0	0	0	0	0
Read/Write	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				Output d	lata for po	rt 8 pins		
P9DDR—Port	9 Data Di	rection R	egister		H'FFC0			Port
Bit	7	6	5	4	3	2	1	0
	P97DDR	P96DDR	P95DDR	P94DDR	P93DDR	P92DDR	P91DDR	P90DDR
Mode 1	L	1		1		1	I	
Initial value	0	1	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W
Modes 2 and	3							
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W
		S	pecification	n of input o	or output fo	or port 9 pi	ins	
P9DR—Port 9	Data Reg	ister			H'FFC1			Port
Bit	7	6	5	4	3	2	1	0
	P97DR	P96DR	P95DR	P94DR	P93DR	P92DR	P91DR	P90DR
Initial value	0	*	0	0	0	0	0	0
Read/Write	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W

Output data for port 9 pins

Note: * Determined by state of pin P96.



contents match TCNT value

ADCR—A/D) Co	ontrol R	egister			H'FFE9	A /	D Converter		
Bit		7	6	5	4	3	2	1	0	
	-	TRGS1	TRGS0	_	_				_	
Initial value	•	0	0	1	1	1	1	1	1	
Read/Write	9	R/W	R/W	—	—	—	—	_	—	
1	Time	er trigger	select							
0 0 Start of A/D conversion by external trigger is disabled										
1 Start of A/D conversion by external trigger is disabled										
	1	0	Start of A	/D conver	sion by ex	ternal trigg	ger (8-bit ti	mer) is en	abled	

1 Start of A/D conversion by external trigger pin is enabled



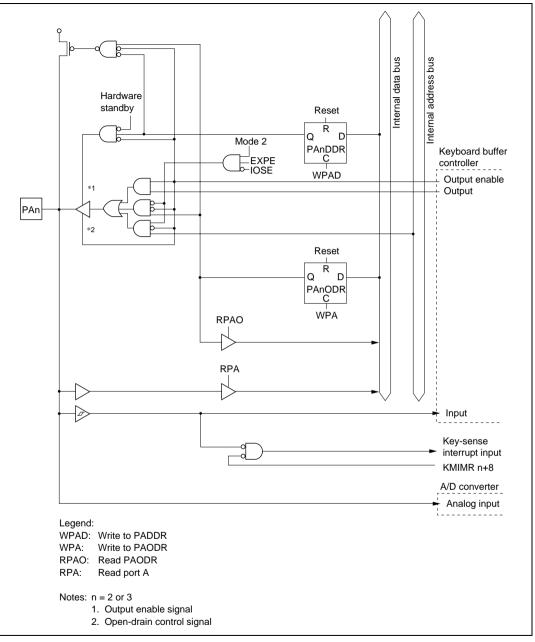


Figure C.35 Port A Block Diagram (Pins PA2, PA3)